

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Amitay Levi, Gian Sharma

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Title: METHOD OF CMP PLANARIZING WAFER TOPOLOGY

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Clara Ragan

**PRELIMINARY AMENDMENT**

BOX PATENT APPLICATION

Assistant Commissioner for Patents

Washington, DC 20231

Sir/Madam:

Prior to prosecution of the above-identified application, please amend this application as follows:

Please add the following claims:

2. A method of polishing a first material on a second material of a semiconductor die, wherein said die having a planar surface, said method comprising:

forming a layer of said second material on said planar surface wherein said layer of said second material having a top surface, substantially parallel to said planar surface;

forming a layer of said first material on said top surface, wherein said layer of said first material varying in a height direction above said top surface;

forming a mask across the die, wherein said mask having a plurality of locations with